AllA Erawa Viacad

(703) 402-4375

AllAViacad@GMail.com

**Title:**

Xenon Laser Constructor

**Field of the Invention:**

The present invention relates to a Xenon Laser Acid Etcher Designed To Build Mercury Infused Chips/Parts To Build The Xenon Constructor Which Is 1 Step Below The Universal Constructor Shown In The Video Game Series Deus Ex Which Builds Everything With Angstromscopic Precision Another words Atomically Perfect Precision While The Xenon Laser Acid Etcher Builds Only 3-D Objects Made Of Any Previously Provided Materials Down To Nanometer Precision.

**Description of the Prior Art{MUST READ FIRST}:**

 Chips Are Generally Made With Photo-Lithography Involving A Circuit Printed Mask Which Allows Light From A Xenon Lamp To Dissolve The Silicon DiOxide Layer Which Is Washed Away By A Water Stream Film, Then Acid Is Injected Into The Water Film To Wash Away The Silicon DiOxide Layer Before The Water Film Layer Becomes Neutral Preventing The Silicon From Being Etched Further. Because Of The Orientation Of The Singular Crystal Layer Of Silicon Or Diamond Generally, Acid, H+, Does Not Get To Dissolve Horizontally In Any Direction Keeping The Silicon Etched Squarely. This Process Can Build Robotic Fingers, Hands, Arms, Gear Assemblies, As Well As Positive Molds For Metals To Produce Negative Molds For Clear Plastics Involved With Xenon Lasers Which Source Light Into A Highly Acute(low angled) Cone Of Fiber For Use In Cutting Things From Far Away Or A Helium Cooled Laser Channel Built Of Such Built Fiber Or A Carbon/Nitrogen/Other Nanotube To Build Things Close Up Within A Xenon Laser Constructor.

Mercury Is Injected Into Certain Portions Of The Etched Circuit And Ion Dopers Which Consist Of A Micro-Tipped Positive Or Negative Element Charged Positively And Put Near The Etched Silicon To Make Silicon Transistors, Then Metal Leads Are Stamped Into Certain Female Etched Notches Then Mercury Injected To Connect Said Leads To The Rest Of The Pattern Circuit. Then Hard Plastic Encases The Chip Which Is Generally Soldered To A Chip Board.

**Summary of the Invention: Xenon Laser Constructor**

**Chip Constructor**

Computer chips are manufactured in a fully fully fully clean room that is evacuated to the point of having virtually absolutely no air particles in the chip farm room. Chips are created by using xenon Lasers to etch a singular silicon crystal(broken into a wafer by an extremely thin katana) so that the mild acid bath etches vertically(the silicon chip is parallel to the ground) and not horizontally due to the angle of the Silicon Diamond Cubic Lattice which stops the acid from etching horizontally. A large Xenon Light is surrounded by conical hexagonal chrome light catchers which direct the light into fiber optic laser channels which become gradually thinner to flat ends. Using a Spin Forged Katana tip any size of hole for the Xenon Laser can be produced by poking properly angled holes in an opaque plastic and layering the hexagonal matrix of holes so that the light is stopped unless it is shining through the holes. The angled lasers can be controlled by a series of mirrors to direct them onto the newly produced Silicon Circuit. The Mirrors and Chip Mount are rotated and moved respectively by a large amount of small gears that has to be assembled by machine. The rectangular prismal holes on the silicon chip are made when the xenon lasers scan over the silicon heating up the acid increasing the reaction rate to make it dissolve the silicon vertically because of the Silicon crystal arrangement stopping horizontal breakdown due to atoms of the silicon keeping the acid from passing horizontally. Wires are melted into the holes and the excess along with a thin layer of silicon(so that the metal does not create N-type silicon) cut away by katana and a new wafer layer added on by a delicate suction mover(Silicon breaks along the crystal angle that is exactly perpendicular to etching direction). Mercury could be used instead if you don't think the above works. Silicon is usually doped with Boron(To Make P-Type Anodes in a transistor or diode) and Phosphorus(To Make N-Type Anodes in a transistor or diode) from equally thin metallic tips which electrically(meaning making the pallet an equivalent charge as the element's electronegativity to attract the atoms to the reverse charged tip and making the Silicon the reverse charge to cause the atoms to jump from the tip to the wafer) remove Boron and Phosphorus from a nearby pallet and then electrically transfer them to the silicon wafer.

**Xenon Constructor**

 Ideal Down To The Nanometer But Not The Atom Or Angstrom

Xenon Laser Acid Etched/UC/(C)SRN Built Silicone/Diamond/Memory Crystal Positive Mold Builder To Ceramic/Memory Crystal Mold Negative, Ideal {Impurity}/Nanotubularly Reinforced Alloy Colored SINSS, Wood, Gem, Metal, Stone Plastic, Wood, Other Material Or Combination Of Said Product Material, Injection Molding Apparatus w/ Laser Cut Mold Spot Remover, MultiArmed(Center First Then Outwards In General Circle) Varyated Grid Movement Robotically Placed Forged Metal Variably Shaped In True Prismally Shaft Snapper Onner| After Which Said Circle Of Shafts Are Tritium Cooled To Prevent Large Nucleation Crystals From Weakening Emblem/Emblem High Powered White Laser Cut Layers Perpendicular To Shaft Length Being Produced.

**Laser Constructor**

 Ideal Down To The Nanometer But Not The Atom Or Angstrom

 And Not Jagged Inlets Without Silicone Positive Component Seal Molding Processes{Sipocseam} White Laser Cut Variably Shaped Shafts/Shards/Shards With Inlets In Them That Can Be Cut As Tiltable Cones With The Cones Falling Down And ReCut Over And Over Again

MultiArmed(Center First Then Outwards In General Sphere/Circle) Varyated Grid Movement Robotically Placed Forged Metal Said Shards Then Silicone Robotic Hands Are Laser Cut From Shards And Potential Materials After Which Said Sphere/Circle Of Shards Are Tritium Cooled To Prevent Large Nucleation Crystals From Weakening Product.

**Brief Description of the Drawing:**

 No Drawings Are Provided Because Of Safety Reasons As Invention Is Microscopic And People May Think It Will Look Like Drawing Touch Where Actual Microscopic Invention Is And Get Their Hand Shredded Into A Million Pieces Literally. The Invention Has To Be Build From Xenon Laser Acid Etched Parts From Conventional Chip Builders Then Will Build Itself Kind Of Like In Terminator 2. Thus It Can Be Sold Cheaply To Everybody, It Just Does Not Open The Door To The Production Section Until Thing Produced By Xenon Laser Constructor Is Built Cut From Floor Of Constructor Section Picked Up By Robotic Hands, Insanely Dangerous Constructor Section Sealed By Metal Conveyor Belt Driven Chamber Floor{1 Side Empty And Just Rolled On, The Other The Safe To Touch Chamber Floor}, And Placed Back On Metal Conveyor Belt Floor.

**Detailed Description of the Preferred Embodiments:**

 Same As Summary of the Invention And Description Of Drawing.

**I claim the following:**

1. Chip Constructor

2. Xenon Constructor.

3. Laser Constructor.

4. Xenon Laser Constructor Which Combines All 3 Of The Above In One System.

**Abstract:**

 Lasers, Robotic Arms/Hands, Injection Molding, Ion Doping, To Build Anything From ***Internally* 3-D** Computer Chips To Other Xenon Laser Constructors, Which Build Anything That Is Built Of Atoms That Is 1 nm In Precision.